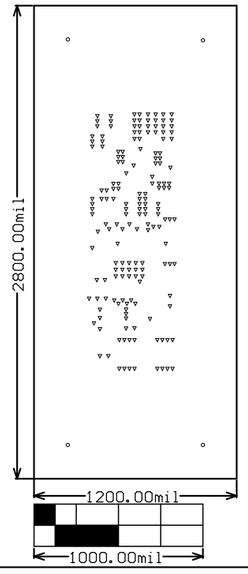
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.50mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric 1	FR-4	9.10mil	4.2	
5	Inner Layer 1	Copper	2.80mil		
6	Dielectric 2	FR-4	30.80mil	4.2	
7	Inner Layer 2	Copper	2.80mil		
8	Dielectric 3	FR-4	9.10mil	4.2	
9	Bottom Layer	Copper	2.80mil		
10	Bottom Solder	Solder Resist	0.50mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 0.13mm
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.127mm (5MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [ ] FR-4 High Tg [X] OTHER FR-4
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	170	10.00mil (0.254mm)	PTH	Round
○	4	125.98mil (3.200mm)	PTH	Round
	174 Total			

TEXAS INSTRUMENTS

PROJECT TITLE: 50W Buck-Boost
DESIGNED FOR: Public Release
FILE NAME: PMP10726_TID.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10726	REV: REVC	SVN REV: Not In VersionControl
LAYER NAME = Mechanical 99	TID #: PMP10726		
PLOT NAME = Fabrication Drawing	GENERATED : 8/1/2016 11:39:28 AM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
J Doong	J Doong
SCALE: 1.12	ALTIUM DESIGNER VERSION: 16.1.11.255